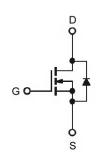


N-Channel 800-V (D-S) MOSFET

Description

The device is using advanced Super-Junction technology. This advanced technology has been especially tailored to minimize conduction loss, provide superior switching performance and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for AC/DC power conversion in switching mode operation for higher efficiency.

Graphic Symbol



Features

- 11A, 800V, $R_{DS(ON)typ} = 0.46\Omega@V_{GS} = 10V$
- Low Gate Charge (typical 38nC)
- High Ruggedness
- Fast Switching
- 100% Avalanche Tested
- Improved dv/dt Capability

•

Typical Applications

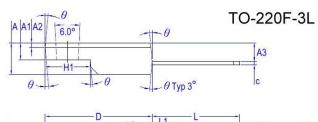
- Switching Mode Power Supply
- Adapter / Charger
- Server Power

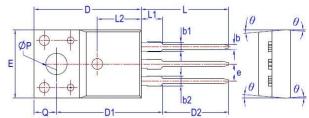
Package type: TO-220



RoHS Compliant

Package Dimension





	Millimeter			Millimeter				
REF.	Min.	Nom.	Max.	REF.	Min.	Nom.	Max.	
Α	4.50	4.70	4.90	D1	15.35	-	15.95	
A1	2.34	2.54	2.74	D2	9.60	9.80	10.15	
A2		0.70REF		E	9.96	10.16	10.36	
A3	2.56	2.76	2.96	е	2.54BSC			
b	0.70	-	0.90	H1	6.48	6.68	6.88	
b1	1.18	-	1.43	L	12.68	12.98	13.28	
b2	-	-	1.55	L1	-	-	3.50	
С	0.40	0.50	0.65	ФР	3.06	3.18	3.28	
D	15.57	15.87	16.17	Q	3.15	-	3.45	



N-Channel 800-V (D-S) MOSFET

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings						
Symbol	Parameter	Value	Units			
V_{DS}	Drain-Source Voltage	800	V			
V _G S	Gate-Source Voltage	±30	V			
l _D	Continuous Drain Current¹ (T _C =25°C)	11	А			
	Continuous Drain Current¹ (T _C =100°C)	6.7	Α			
I_{DM}	Pulsed Drain Current ^{1,2}	30	Α			
las	Single Pulse Avalanche Current, L =79mH³	2.1	Α			
Eas	Single Pulse Avalanche Energy, L =79mH³	132	mJ			
dv/dt	Peak Diode Recovery dv/dt	50	V/ns			
D-	Power Dissipation ⁴ (T _C =25°C)	31	W			
P _D	Derating Factor Above 25°C	0.25	W/°C			
TJ/TstG	Operating Junction and Storage Temperature	-55 to +150	°C			

Thermal Resistance Ratings					
Symbol	Parameter	Maximum	Units		
$R_{\theta JA}$	Maximum Junction-to-Ambient ¹	80	°C/W		
Rejc	Maximum Junction-to-Case ¹	4.0	°C/W		

Electrical Characteristics (T _J =25°C unless otherwise specified)							
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units	
$V_{GS(th)}$	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	2.5	-	4.5	V	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250µA	800	-	-	V	
BV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, referenced to 25°C	-	0.6	-	V/°C	
I _{GSS}	Gate-Source Leakage Current	V _{DS} =0V, V _{GS} =±30V	-	-	±100	nA	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =800V, V _{GS} =0V, T _C =25°C V _{DS} =640V, V _{GS} =0V, T _C =125°C	-	-	1 10	μA	
R _{DS} (on)	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =5.5A	-	0.46	0.5	Ω	



N-Channel 800-V (D-S) MOSFET

Dynamic							
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units	
Qg	Total Gate Charge ²	V _{DS} =640V		38			
Qgs	Gate-Source Charge	I _D =11A		4		nC	
Qgd	Gate-Drain Charge	V _{GS} = 10V		4.4			
td(on)	Turn-On Delay Time ²	V _{DS} =400V		26			
tr	Rise Time	I _D =5.5A		60			
td(off)	Turn-Off Delay Time	V _{GS} =10V		75		ns	
tf	Fall Time	$R_G = 25\Omega$		44			
Ciss	Input Capacitance	V _{DS} =100V		680			
Coss	Output Capacitance	V _{GS} =0V		140		pF	
Crss	Reverse Transfer Capacitance	f =1.0MHz		5			

Source-Drain Diode							
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units	
Is	Continuous Source Current ^{1,5}	V V OV 5 O	-	-	11		
I _{SM}	Pulsed Source Current ^{2,5}	V _G =V _D =0V, Force Current	-	-	30	Α	
V _{SD}	Diode Forward Voltage ²	I _S =11A, V _{GS} =0V, T _J =25°C	-	-	1.5	V	
t _{rr}	Reverse Recovery Time ²	I _S =11A, V _{GS} =0V, dI _F / dt =		270		ns	
Qrr	Reverse Recovery Charge ²	100A/µs		3.3		μC	

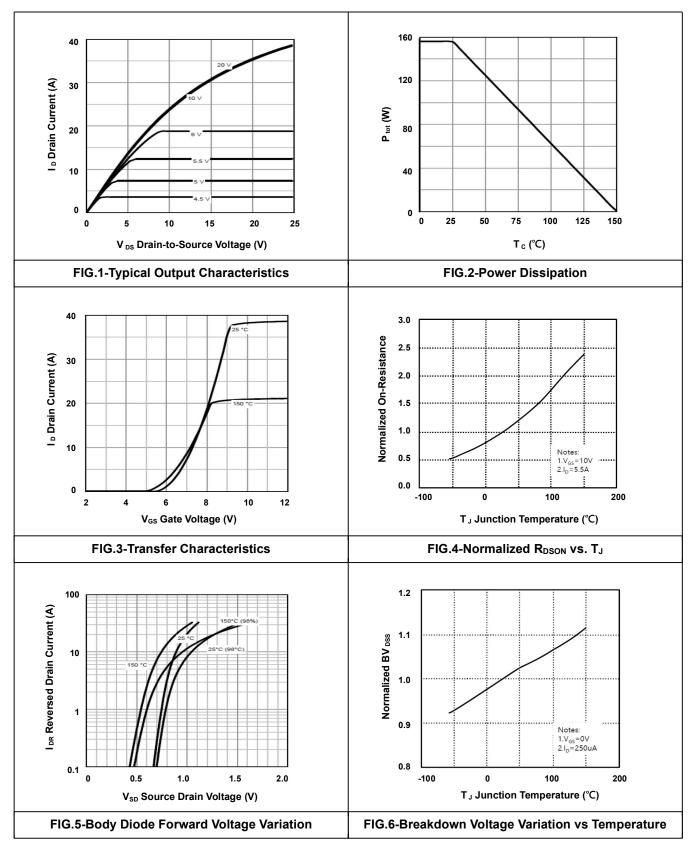
Notes

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2. The data tested by pulsed, pulse width \leq 300us, duty cycle \leq 2%.
- 3. The EAS data shows maximum rating. The test condition is V_{DD} =100V, L=79mH, I_{AS}=2.4A.
- 5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



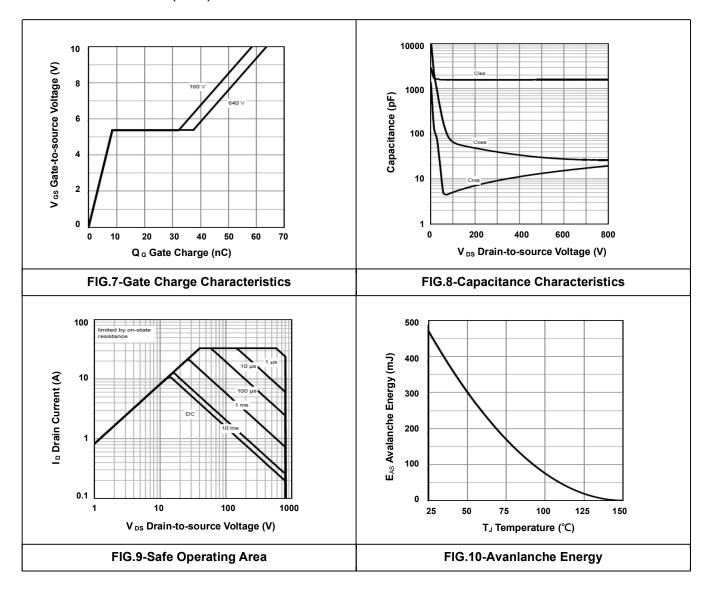
N-Channel 800-V (D-S) MOSFET

• Typical Electrical Characteristics





N-Channel 800-V (D-S) MOSFET





N-Channel 800-V (D-S) MOSFET

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